



**RESPONSE UNDER 37 C.F.R. § 1.116**  
**EXPEDITED PROCEDURE – Art Unit 2827**  
Attorney Docket No. 108298531US

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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: David J. Corisis et al.  
APPLICATION No.: 09/644,476  
FILED: August 23, 2000  
FOR: **METHOD AND APPARATUS FOR  
DECOUPLING CONDUCTIVE PORTIONS  
OF A MICROELECTRONIC DEVICE  
PACKAGE**

EXAMINER: David E. Graybill  
ART UNIT: 2827  
CONF. No: 2634

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**Amendment Under 37 C.F.R. § 1.116**

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The present communication responds to the Office Action dated September 19, 2002, in the above-identified application. Please amend the application as follows. The attached Appendix presents a marked-up version of the changes made to the claims by the current amendment.

**In the Claims:**

Please cancel claims 13, 15, 17-37 and 39. Please amend claims 1, 14 and 16 as follows. Please add new claims 62-67. Following is a complete listing of the claims pending in the application, as amended:

1. (Amended) A method for packaging a microelectronic substrate, comprising:

positioning a conductive member at least proximate to the microelectronic substrate, the conductive member having first and second neighboring